ABSTRACT

Improved System for Substrate Processing

A method of processing IC units comprising the steps of: dicing said IC units from a substrate; delivering said IC units to a idle block; inspecting a face of said units as exposed during the dicing step using an inspection device whilst said units are on said idle block, then; engaging said units with a picker assembly; passing said units over a second inspection device to inspect an opposed face of said units.

Figure 2

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